

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

REQUEST FOR ACCESS TO AN ABANDONED APPLICATION UNDER 37 CFR 1.14

Bring completed form to:
File Information Unit, Suite 3A20
2800 South Randolph Street
Arlington, VA 22206
Telephone: (703) 756-1800

In re Application of

JUN 16 2011

Application Number

08/949 850

Filed

10/14/97

Paper No.

#33

I hereby request access under 37 CFR 1.14(a)(1)(iv) to the application file record of the above-identified ABANDONED application, which is not within the file jacket of a pending Continued Prosecution Application (CPA) (37 CFR 1.53(d)) and which is identified in, or to which a benefit is claimed, in the following document (as shown in the attachment):

United States Patent Application Publication No. _____, page, _____, line _____

United States Patent Number 6559379, column _____, line _____

WIPO Pub. No. _____, page _____, line _____

Related Information About Access to Applications Maintained in the Image File Wrapper System (IFW) and Access to Pending Applications in General

A member of the public, acting without a power to inspect, cannot order applications maintained in the IFW system through the FIU. If the member of the public is entitled to a copy of the application file, then the file is made available through the Public Patent Application Information Retrieval system (Public PAIR) on the USPTO internet web site (www.uspto.gov). Terminals that allow access to Public PAIR are available in the Public Search Room. The member of the public may also be entitled to obtain a copy of all or part of the application file upon payment of the appropriate fee. Such copies must be purchased through the **Office of Public Records** upon payment of the appropriate fee (37 CFR 1.19(b)).

For published applications that are still pending, a member of the public may obtain a copy of:

the file contents; the pending application as originally filed; or any document in the file of the pending application.

For unpublished applications that are still pending:

- (1) If the benefit of the pending application is claimed under 35 U.S.C. 119(e), 120, 121, or 365 in another application that has: (a) issued as a U.S. patent, or (b) published as a statutory invention registration, a U.S. patent application publication, or an international patent application publication in accordance with PCT Article 21(2), a member of the public may obtain a copy of: the file contents; the pending application as originally filed; or any document in the file of the pending application.
- (2) If the application is incorporated by reference or otherwise identified in a U.S. patent, a statutory invention registration, a U.S. patent application publication, or an international patent application publication in accordance with PCT Article 21(2), a member of the public may obtain a copy of the pending application as originally filed.

Brian S. Willingham

Signature

Brian S. Willingham

Typed or printed name

6/16/11

Date

FOR PTO USE ONLY

Approved by BSW

(initials)

Unit: File Information Unit

Brian S. Willingham

This collection of information is required by 37 CFR 1.11 and 1.14. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. BRING TO: File Information Unit, Suite 3A20, 2800 South Randolph Street, Arlington, Virginia.

If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.



US006559379B2

(12) **United States Patent**
Solanki et al.

(10) Patent No.: **US 6,559,379 B2**
(45) Date of Patent: **May 6, 2003**

(54) **PRESSURE SENSOR WITH TRANSDUCER MOUNTED ON A METAL BASE**

(75) Inventors: Dinesh Solanki, Santa Clara, CA (US); Janusz Bryzek, Fremont, CA (US)

(73) Assignee: NovaSensor, Inc., Fremont, CA (US)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

(21) Appl. No.: **09/815,900**

(22) Filed: **Mar. 22, 2001**

(65) **Prior Publication Data**

US 2001/0009195 A1 Jul. 26, 2001

4,984,466 A	1/1991	Yasui et al.
5,139,973 A	8/1992	Nagy et al.
5,207,102 A	5/1993	Takahashi et al.
5,239,806 A	8/1993	Maslakow
5,263,241 A	11/1993	Hart, Jr. et al.
5,263,242 A	11/1993	Singh Deo et al.
5,289,344 A	2/1994	Gagnon et al.
5,386,342 A	1/1995	Rostoker
5,394,751 A	3/1995	Ishibashi
5,424,249 A	6/1995	Ishibashi
5,436,407 A	7/1995	Fehr et al.
5,436,492 A	7/1995	Yamanaka
5,436,500 A	7/1995	Park et al.
5,457,341 A	10/1995	West
5,471,011 A	11/1995	Maslakow
5,483,098 A	1/1996	Joiner et al.
5,483,740 A	1/1996	Maslakow
5,543,657 A	* 8/1996	Diffenderfer et al. 257/666
5,760,467 A	* 6/1998	Itihasi 257/676
6,303,985 B1	* 10/2001	Larson et al. 257/676

Related U.S. Application Data

(63) Continuation of application No. 08/949,850, filed on Oct. 14, 1997, now abandoned, which is a continuation of application No. 08/393,956, filed on Feb. 24, 1995, now abandoned.

(51) Int. Cl. ⁷ H05K 5/06
(52) U.S. Cl. 174/52.2; 174/52.4; 257/676
(58) Field of Search 174/52.2, 52.4; 257/676, 675, 712, 713; 73/727, 756

(56) **References Cited**

U.S. PATENT DOCUMENTS

4,649,415 A	3/1987	Hebert
4,655,088 A	4/1987	Adams
4,686,764 A	8/1987	Adams et al.
4,850,227 A	7/1989	Luettgen et al.

FOREIGN PATENT DOCUMENTS

DE	32 00 448	7/1983
EP	0 286 867	10/1988

* cited by examiner

Primary Examiner—Hung V. Ngo

(74) Attorney, Agent, or Firm—Morrison & Foerster LLP

(57) **ABSTRACT**

A three piece housing, designed to house semiconductor chips is molded using a polymer material. The chip sits on a metal base. Electrical leads pass through a molded housing to provide electrical contact between the semiconductor chip and external circuitry.

31 Claims, 5 Drawing Sheets

